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R8C/11、R8C/13群

应用商用频率的高速内部振荡器频率的调整

1. 概要

本资料说明了通过商用频率（50Hz/60Hz）来调整高速内部振荡器频率的程序。

2. 前言

本资料中说明的应用例，适合以下单片机在下列条件下使用。

- 单片机 : R8C/11、R8C/13群
- RAM容量、ROM容量 : 1K字节/16K字节

和R8C/11群有相同的SFR（外围设备控制寄存器）的其它的R8C/Tiny系列也可以使用本程序。但有时会因增加一部分功能等而有所改变,所以必须通过手册进行确认。在使用本应用说明时必须进行充分的评价。

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3. 应用例的说明

3.1 高速内部振荡器的概要

R8C/11 群搭载约 8MHz 的高速内部振荡器。内部振荡器由于工作温度、电源电压等外部因素，工作频率产生变化。可通过设定 HR1 寄存器调整频率。

HR1 寄存器的值和高速内部振荡器的周期的关系如下。但因各个位的延迟量不完全相同，所以必须进行调
整以使各个位发生变化。另外，必须将 bit7 清 “0”。

$$\text{高速内部振荡器的周期} = \text{td}(\text{HRoffset}) + \left(\text{b6} + \frac{\text{b5}}{2} + \frac{\text{b4}}{4} + \frac{\text{b3}}{8} + \frac{\text{b2}}{16} + \frac{\text{b1}}{32} + \frac{\text{b0}}{64} \right) \times \text{td}(\text{HR})$$

在本应用说明中对使用商用频率（50MHz/60MHz）的高速内部振荡器进行频率调整。

3.2 程序概要

使用商用频率调整高速内部振荡器频率的方法如下所示。

通过将高速内部振荡器作为计数源的定时器C来测定商用频率。为使测定值和理论值匹配，通过调整HR1寄存器，将高速内部振荡器的频率调至8MHz。

理论值可用如下公式求出。

$$\text{定时器C测定的理论值} = \frac{\text{高速内部振荡器的预期频率}}{\text{商用频率} \times \text{高速内部振荡器的分频比}}$$

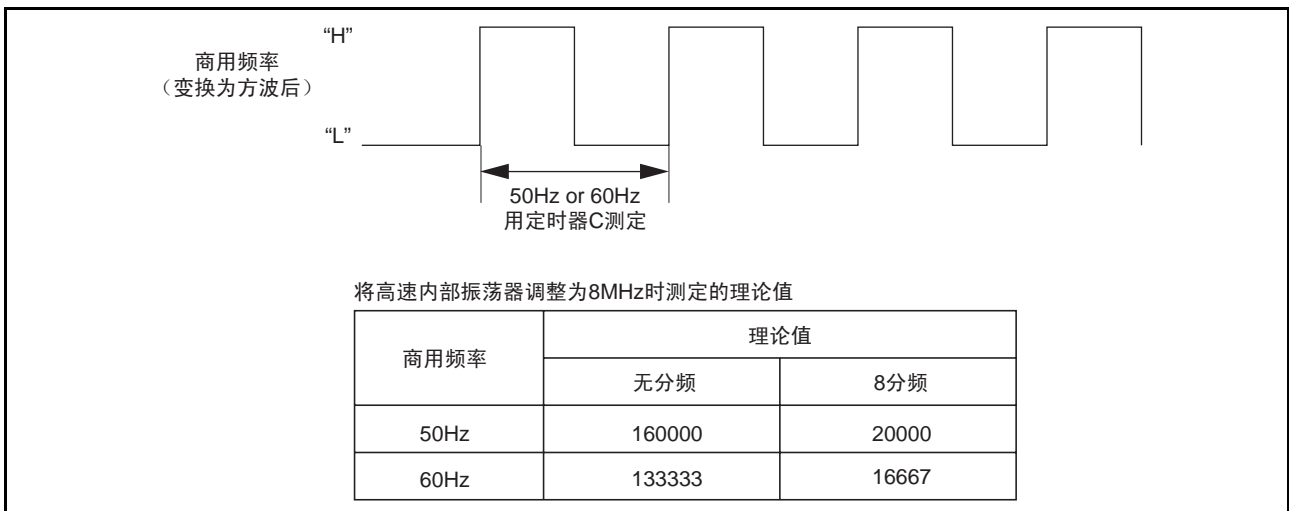


图1 商用频率测定

HR1寄存器的调整率（向HR1寄存器写00h时和写01h时的周期的差）为1ns。HR1寄存器设定为n时的频率可调整为8MHz的情况下，此时HR1的设定值和定时器C的测定值的关系如表1所示。

表1 HR1的设定值和定时器C的测定值

HR1的设定值	高速内部振荡器振荡		定时器C的测定值（60Hz测定时）	
	周期	频率	无分频	8分频
n-2	123ns	8.13MHz	135501	16938
n-1	124ns	8.06MHz	134409	16801
n	125ns	8.00MHz	133333	16667
n+1	126ns	7.94MHz	132275	16534
n+2	127ns	7.87MHz	131234	16404

在本应用说明中，定时器C采用8分频，并将测定结果除以100后和理论值（166）进行比较。当测定结果和理论值匹配时，频率为7.97MHz（定时器C的测定值为16600时）～8.02MHz（定时器C的测定值为16699时）。

初始运行时，进行高速内部振荡器的调整，并将设定值保存到闪存ROM。要避免保存的地址和程序配置块的匹配。样本程序的存储器映像图如图2所示。

在下次之后（保存HR1的调整值后）的运行中，从数据闪存读出HR1寄存器的初始值，并进行设定。此后，每检测到一次商用频率的上升沿就进行一次微调。

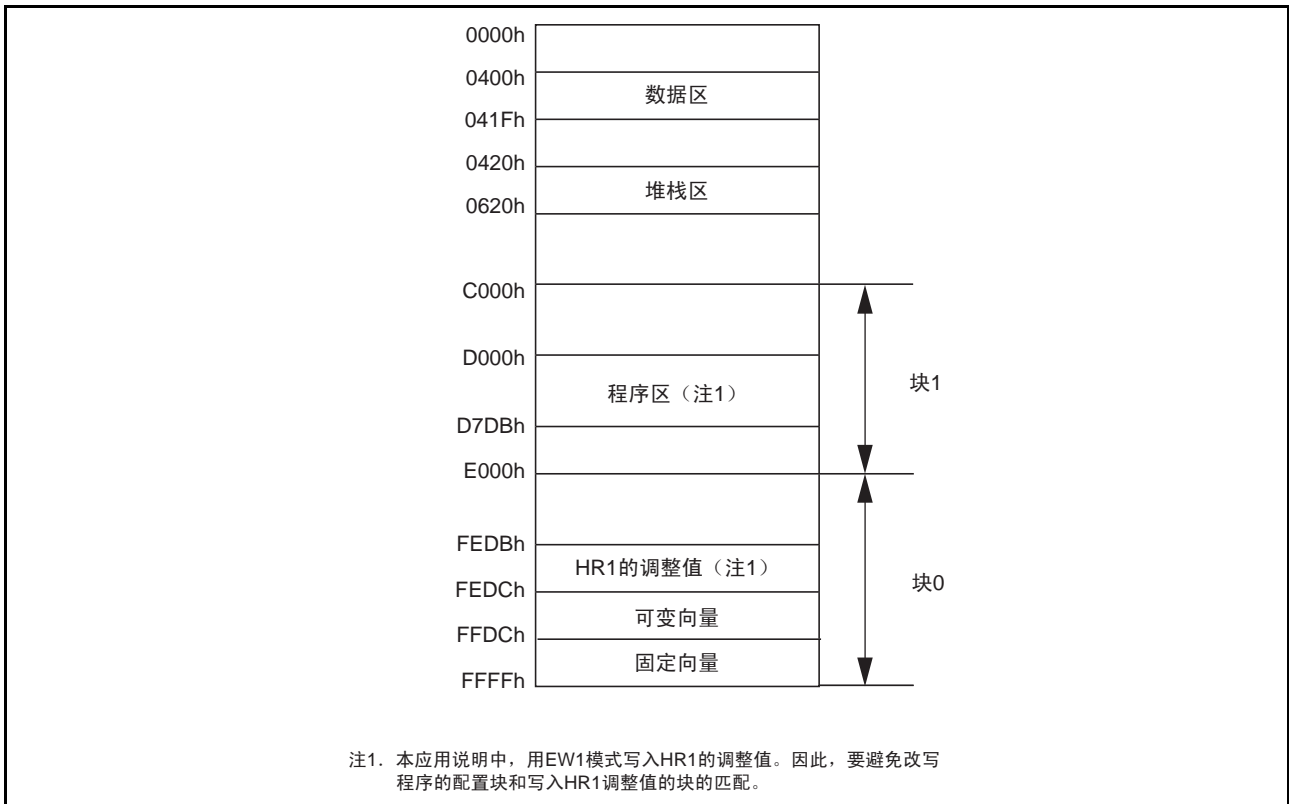


图2 样本程序的存储器映像图

3.3 使用引脚

表2 使用引脚和功能

引脚名	输入/输出	功能
P33/ $\overline{\text{INT3}}$ /TCIN	输入	商用频率（方波）的输入

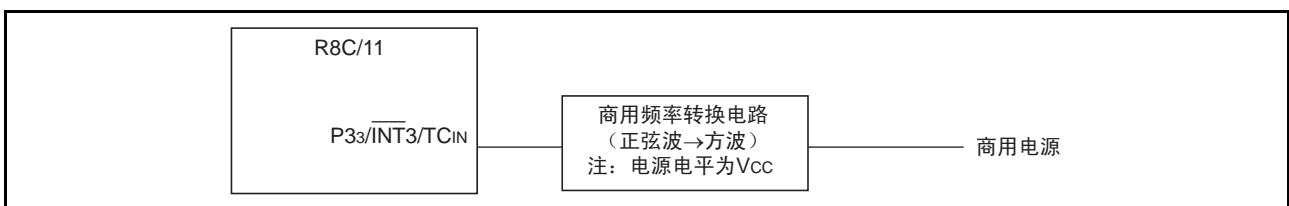


图3 商用频率输入

4. 函数表和流程图

4.1 函数表

声明	void main(void)		
概要	主函数		
参数	参数名		意义
	无		
返回值	类型	值	意义
	无		
功能说明	进行 SFR 的初始设定和 LOOP 处理		

声明	void sfr_init(void)		
概要	SFR 初始化函数		
参数	参数名		意义
	无		
返回值	类型	值	意义
	无		
功能说明	进行 SFR 的初始设定		

声明	void first_hz_adjut(void)		
概要	初始频率调整函数		
参数	参数名		意义
	无		
返回值	类型	值	意义
	无		
功能说明	初始启动时，进行高速内部振荡器的调整		

声明	void write_ringadjust_data(unsigned char data)		
概要	频率调整值写入函数		
参数	参数名		意义
	unsigned char data		调整值
返回值	类型	值	意义
	无		
功能说明	将 HR1 寄存器的调整值写入闪存 ROM		

声明	void flash_open_ew1_mode(void)		
概要	EW1 模式转移函数		
参数	参数名	意义	
	无		
返回值	类型	值	意义
	无		
功能说明	使CPU改写模式（EW1模式）变为有效。		

声明	void flash_close_ew1_mode(void)		
概要	EW1 模式解除函数		
参数	参数名	意义	
	无		
返回值	类型	值	意义
	无		
功能说明	使CPU改写模式无效		

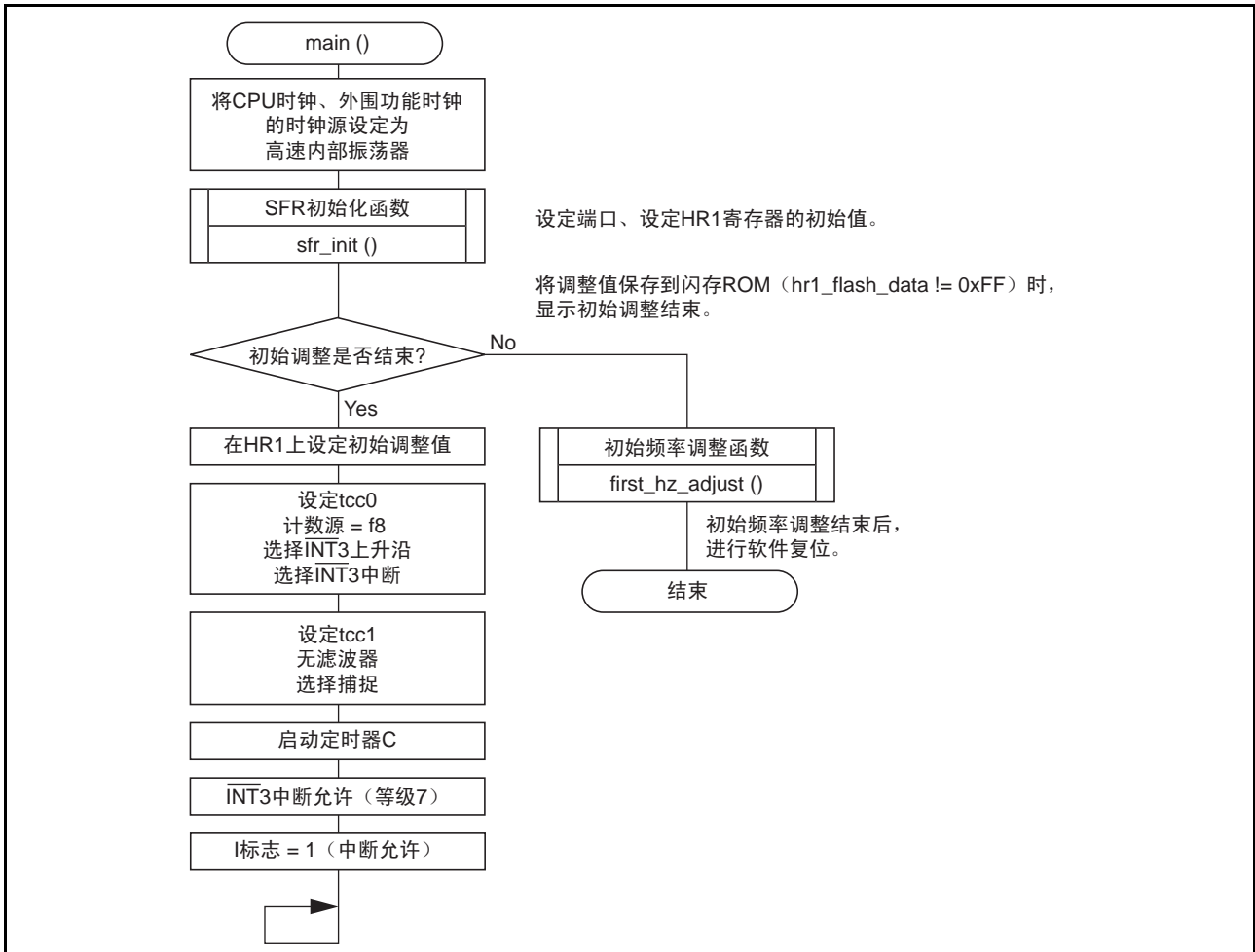
声明	int flash_byte_write(unsigned char *address , unsigned char data)		
概要	闪存写入函数		
参数	参数名	意义	
	unsigned char *address	写入地址	
	unsigned char data	写入数据	
返回值	类型	值	意义
	int	chk_flash_status()	闪存写入状态
功能说明	向写入地址（*address）写入1字节的数据（data）。		

声明	int chk_flash_status(void)		
概要	全状态检查函数		
参数	参数名	意义	
	无		
返回值	类型	值	意义
	int	chk_flash_status()	闪存改写状态
功能说明	进行全状态检查，返回闪存改写状态（正常退出、命令顺序错误、擦除错误、编程错误）。		

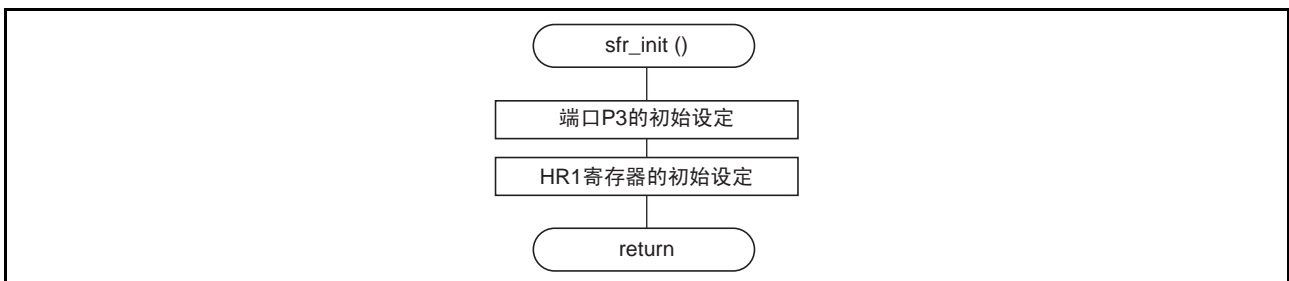
声明	void int3_hz_in(void)		
概要	高速内部振荡器调整函数（INT3中断函数）		
参数	参数名	意义	
	无		
返回值	类型	值	意义
	无		
功能说明	当检测到INT3/TCIN引脚的下降沿时进行中断处理。通过定时器C的测定值进行高速内部振荡器的调整。		

4.2 流程图

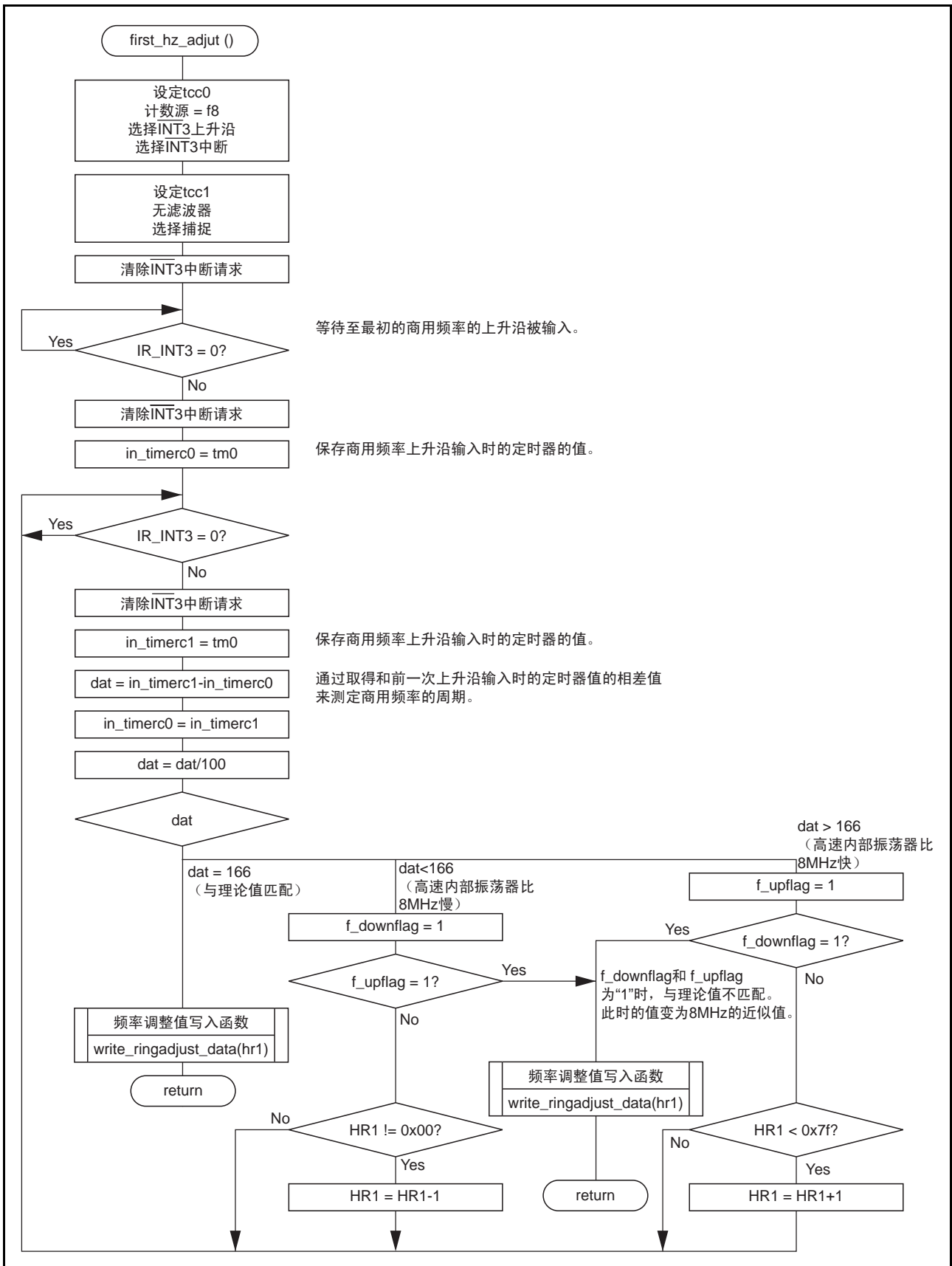
4.2.1 主函数



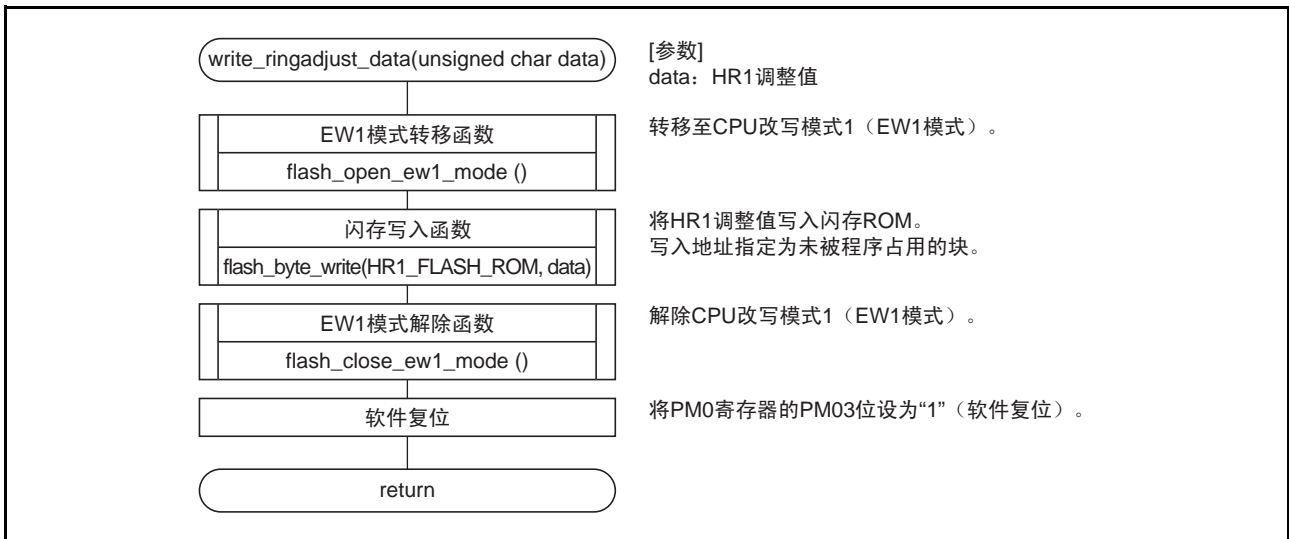
4.2.2 SFR初始化函数



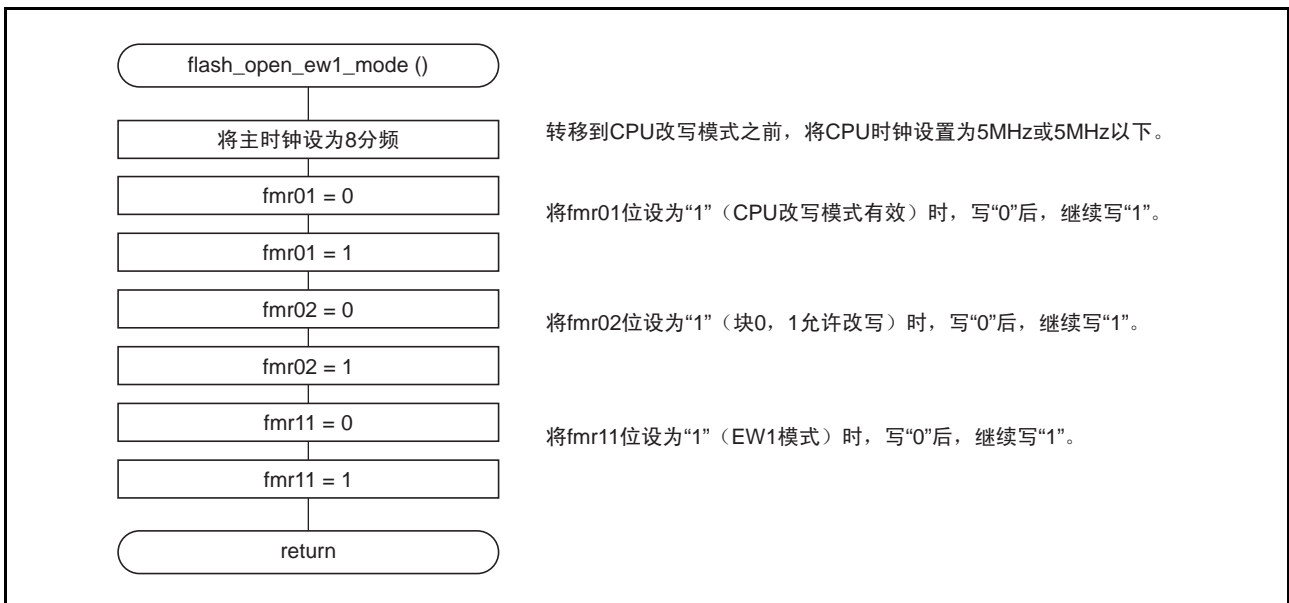
4.2.3 初始频率调整函数



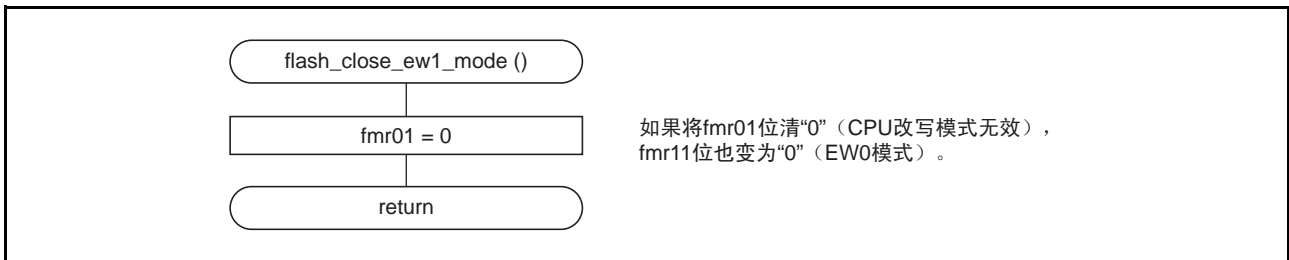
4.2.4 周期频率调整值写入函数



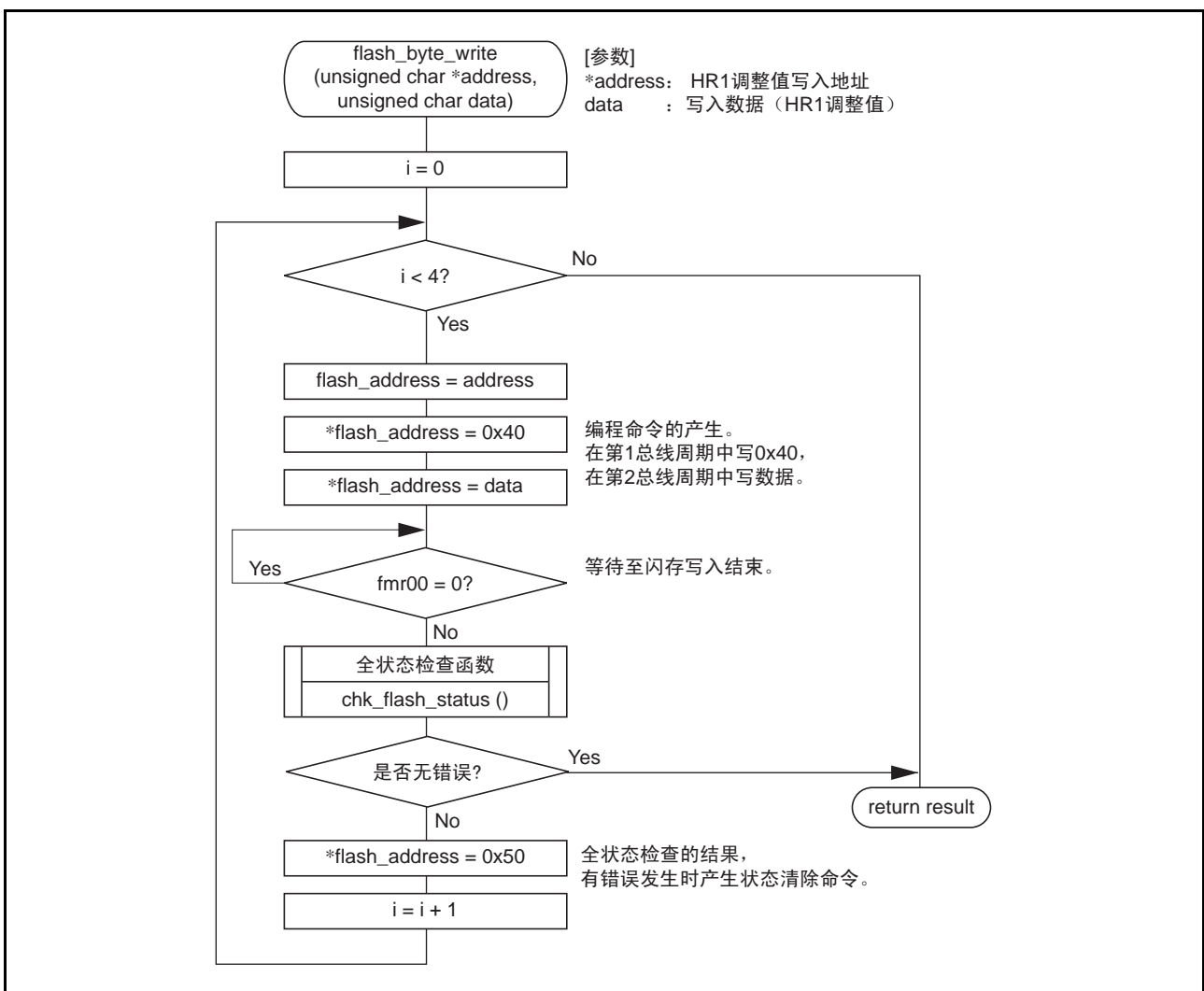
4.2.5 EW1 模式转移函数



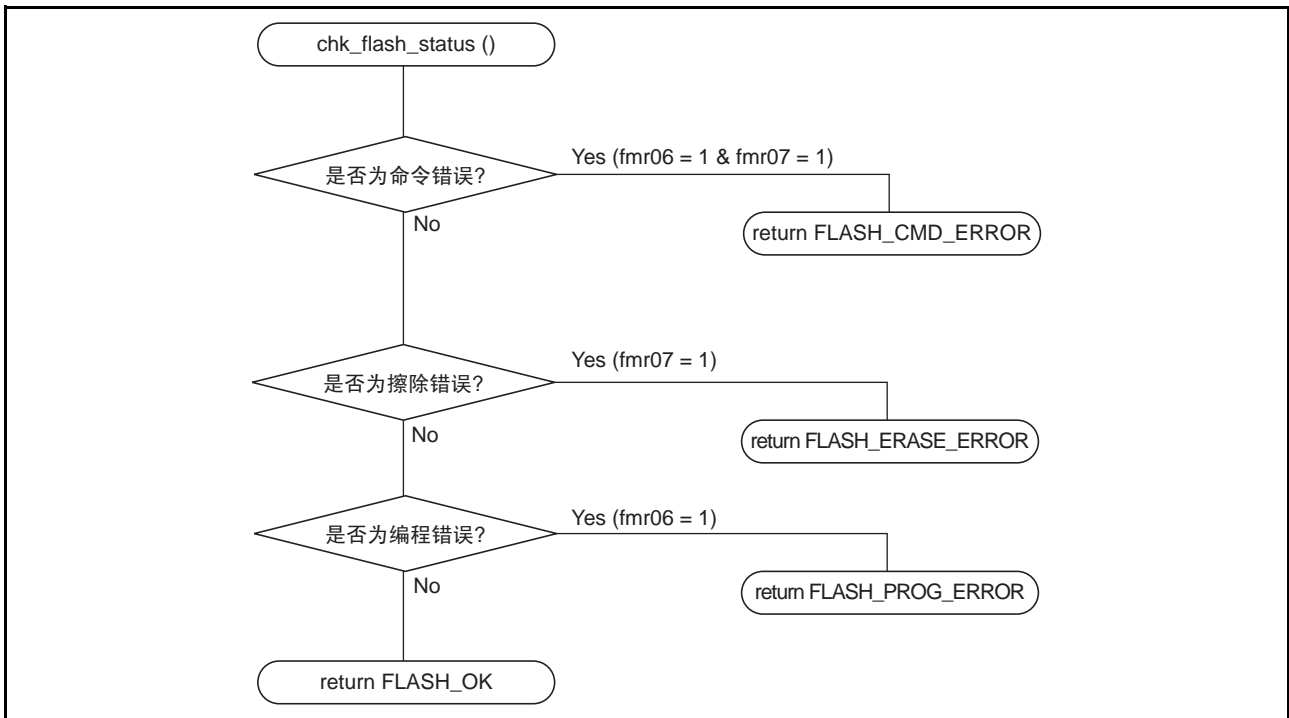
4.2.6 EW1 模式解除函数



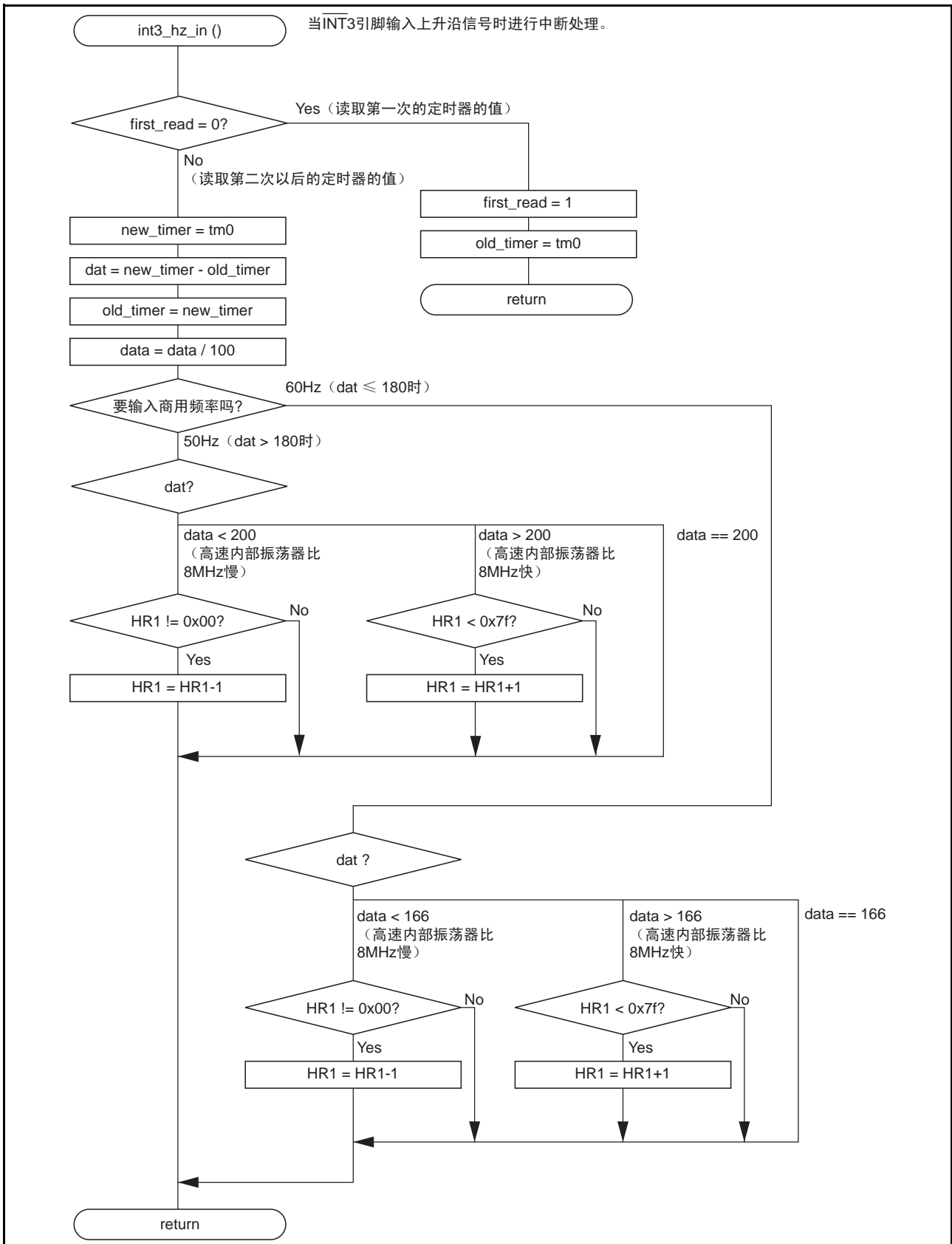
4.2.7 闪存写入函数



4.2.8 全状态检查函数



4.2.9 高速内部振荡器调整函数 (INT3 中断函数)



5. 参考程序例

样本程序如下所示。

```

/*****
*
*   File Name      : main.c
*   Contents       : Main program of High frequency judgement R8C/11 Group
*   Copyright, 2004 RENESAS TECHNOLOGY CORPORATION
*                   AND RENESAS SOLUTIONS CORPORATION
*                   All rights reserved
*   Version        : 1.00
*****/
/*****
*   include file
*****/
#include "sfr_r811.h"          /* Definition of the R8C/11 SFR */
#include "sfr_r811_flash.h"  /* Definition of the R8C/11 flash SFR */

/*****
*   prototype definition
*****/
void sfr_init(void);
void first_hz_adjut(void);
void write_ringadjust_data(unsigned char);
void flash_open_ewl_mode(void);
void flash_close_ewl_mode(void);
int flash_byte_write(unsigned char * , unsigned char);
int chk_flash_status(void);

/*****
*   global label
*****/
unsigned int in_timerc0;      /* input_timerc loading0 */
unsigned int in_timerc1;      /* input_timerc loading1 */
unsigned int dat;            /* frequency */
unsigned int old_timer;      /* input_timerc old loading */
unsigned int new_timer;      /* input_timerc new loading */

union byte_def cnt_flag;
#define f_downflag cnt_flag.bit.b0 /* Hz under flag */
#define f_upflag cnt_flag.bit.b1 /* Hz over flag */
#define HR1_FLASH_ROM ((unsigned char *)0xfedb) /* hr1 adjust data store rom address */
/*****
*   macro definition
*****/
enum{
    FLASH_OK,
    FLASH_CMD_ERROR,
    FLASH_ERASE_ERROR,
    FLASH_PROG_ERROR
};
/*****
Name:          main
Parameters:    None
Returns:       None
Description:   High frequency judgement
*****/
main() {
    /* Setting system clock */
    prc0 = 1;          /* Protect off */
    cm06 = 1;
    cm16 = 0;
    cm17 = 0;          /* 1/1 */
    hr00 = 1;          /* On-chip oscillator on */
    asm("nop");        /* waiting */
    asm("nop");
    asm("nop");
    hr01 = 1;
    cm06 = 0;          /* 1/8 */
    prc0 = 0;          /* Protect on */

```

```

asm("FCLR I"); /* Interrupt disable */

sfr_init(); /* Initial setting of SFR registers */

/* Confirm Adjusting */
if (*HR1_FLASH_ROM == 0xff){
    first_hz_adjut();
}
}else{
/* Setting high-speed on-chip oscillator control register1 */
prc0 = 1; /* Protect off */
hr1 = *HR1_FLASH_ROM; /* Loading adjust data for flash rom */
prc0 = 0; /* Protect on */

/* Setting timer C inputcapture */
tcc0 = 0x02; /* Setting timer C control register0 */
tcc1 = 0x00; /* Setting timer C control register1 */
tcc00 = 1; /* Timer C start */
int3ic = 0x07; /* interrupt level 7 */
asm("FSET I"); /* Interrupt enable */

while(1){
/* main loop */
}
}
}

/*****
Name: sfr_init
Parameters: None
Returns: None
Description: Initial setting of SFR registers
*****/
void sfr_init(void){

/* Setting port registers */
p3_3 = 0;
/* Setting port direction registers */
pd3_3 = 0; /* INT3 pin input */

/* High-speed on-chip oscillator control register1 */
prc0 = 1; /* Protect off */
hr1 = 0x40;
prc0 = 0; /* Protect on */
}
/*****
Name: first_hz_adjut
Parameters: None
Returns: None
Description: The first high frequency judgement
*****/
void first_hz_adjut(void){

/* Setting timer C inputcapture */
tcc0 = 0x02; /* Setting timer C control register0 */
tcc1 = 0x00; /* Setting timer C control register1 */
tcc00 = 1; /* Timer C start */

ir_int3ic = 0; /* INT3 interrupt request clear */

/* First frequency measure */
while (ir_int3ic == 0); /* Int3 upedge */

ir_int3ic = 0;
in_timerC = tm0; /* Loading timerC */
}

```



```

while(1){
    /* Second frequency measure */
    while (ir_int3ic == 0);          /* int3 upedge */
    ir_int3ic = 0;
    in_timercl = tm0;              /* loading timerC */

    dat = in_timercl - in_timercl0; /* Calculate pulse width */
    in_timercl0 = in_timercl;
    dat = dat / 100;

    /* 60Hz judgement */
    /* Equal to 60Hz */
    if (dat == 166){
        /* flash write & software reset */
        write_ringadjust_data(hr1);
        return;

    /* More than 60Hz */
    }else if (dat < 166){
        f_downflag = 1;
        if (f_upflag == 1){
            /* flash write & software reset */
            write_ringadjust_data(hr1);
            return;
        }
        if (hr1 != 0x00){          /* Minimum of high-speed on-chip oscillator register1 */
            prc0 = 1;              /* Protect off */
            --hr1;                 /* Sub high-speed on-chip oscillator register1 */
            prc0 = 0;              /* Protect on */
        }

    /* Less than 60Hz */
    }else if (dat > 166){
        f_upflag = 1;
        if (f_downflag == 1){
            /* flash write & software reset */
            write_ringadjust_data(hr1);
            return;
        }
        if (hr1 < 0x7f){          /* Maximum of high-speed on-chip oscillator register1 */
            prc0 = 1;              /* Protect off */
            ++hr1;                 /* Add high-speed on-chip oscillator register1 */
            prc0 = 0;              /* Protect on */
        }
    }
}
}

/*****
Name:          write_ringadjust_data
Parameters:    Adjust data
Returns:       None
Description:    Software reset after flash writing
*****/
void write_ringadjust_data(unsigned char data){

    /* Starting of flash write mode */
    flash_open_ewl_mode();

    /* Write a high-speed on-chip oscillator register1 adjusted data ( Retry is 4 times ) */
    flash_byte_write(HR1_FLASH_ROM, data);
    /* Finishing of flash write mode */
    flash_close_ewl_mode();

    /* Software reset */
    prc1 = 1;
    pm03 = 1;
    prc1 = 0;
}

```

```

/*****
Name:          flash_open_ewl_mode
Parameters:    None
Returns:       None
Description:    Open Flash write mode
*****/
void flash_open_ewl_mode(void){

    /* Slow down cpu clock */
    prc0 = 1;
    cm06 = 1;
    prc0 = 0;

    /* Set flash write enable */
    fmr01 = 0;
    fmr01 = 1;                /* CPU writing mode */

    fmr02 = 0;
    fmr02 = 1;                /* writing permission */

    fmr11 = 0;
    fmr11 = 1;                /* EWL mode */
}

/*****
Name:          flash_close_mode
Parameters:    None
Returns:       None
Description:    End of flash write mode
*****/
void flash_close_ewl_mode(void){

    /* Reset flash write enable */
    fmr01 = 0;
}

/*****
Name:          flash_byte_write
Parameters:    Write Address, Write Data
Returns:       flash status
Description:    Write byte data to Flash
*****/
int flash_byte_write(unsigned char *address , unsigned char data){

unsigned char *flash_address;
unsigned char i;
unsigned int result;

    /* Retry 4 times */
    for ( i = 0 ; i < 4 ; ++i ){

        /* Set write address */
        flash_address = address;

        /* Set program mode */
        *flash_address = 0x40;

        /* Write data */
        *flash_address = data;

        /* Finishing data */
        while(fmr00 == 0);

        /* Full status check */
        result = chk_flash_status();
        if( result == FLASH_OK) break;

        /* Clear status */
        *flash_address = 0x50;
    }
    return result;
}

```



```
/* 60Hz judgement */
/* Equal to 60Hz */
if (dat == 166){

/* More than 60Hz */
}else if (dat < 166){
    if (hr1 != 0x00){
        prc0 = 1;
        ++hr1;
        prc0 = 0;
        }
        }

/* Less than 60Hz */
}else if (dat > 166){
    if (hr1 < 0x7f){
        prc0 = 1;
        ++hr1;
        prc0 = 0;
        }
        }
    }
}
```

```
/* Protect off */
/* Add high-speed on-chip oscillator register1 */
/* Protect on */

/* Protect off */
/* Add high-speed on-chip oscillator register1 */
/* Protect on */
```

6. 参考文档

硬件手册

R8C/11 群硬件手册

(最新版请从瑞萨科技公司主页获取。)

公司主页和咨询窗口

有关本应用说明的技术方面的咨询请参考下面的网页。

瑞萨科技公司主页 <http://www.cn.renesas.com>

详细联系方式 https://update.renesas.com/registration/forms/contact_us.jsp

修订记录

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